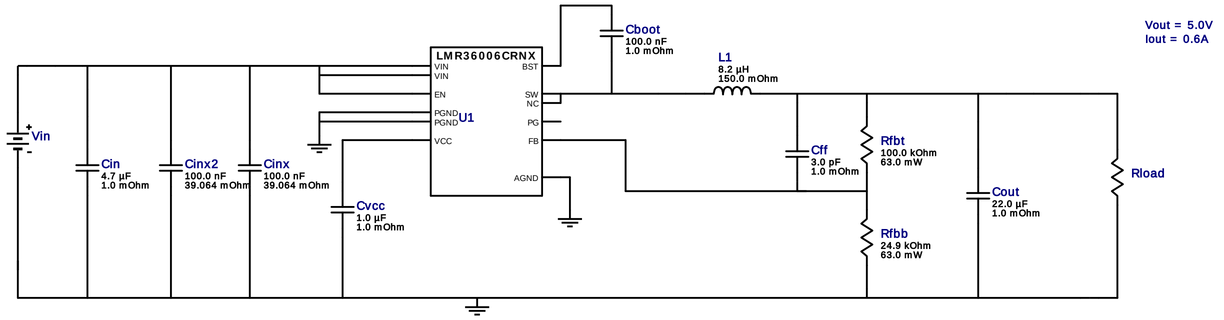
VinMin = 10.0V
VinMax = 24.0V
Vout = 5.0V
Iout = 0.6A

Device = LMR36006CRNXR
Topology = Buck
Created = 2022-02-22 23:49:29.874
BOM Cost = $1.21
BOM Count = 11
Total Pd = 0.89W

WEBENCH ® Design Report

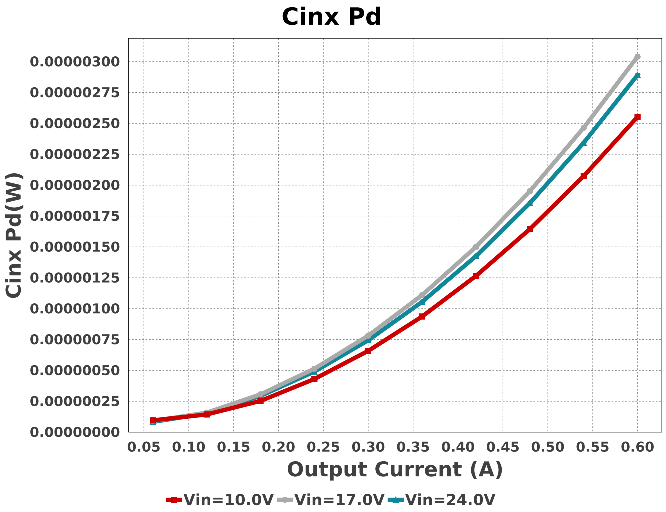
Design : 7 LMR36006CRNXR
LMR36006CRNXR 10V-60V to 5.00V @ 0.6A

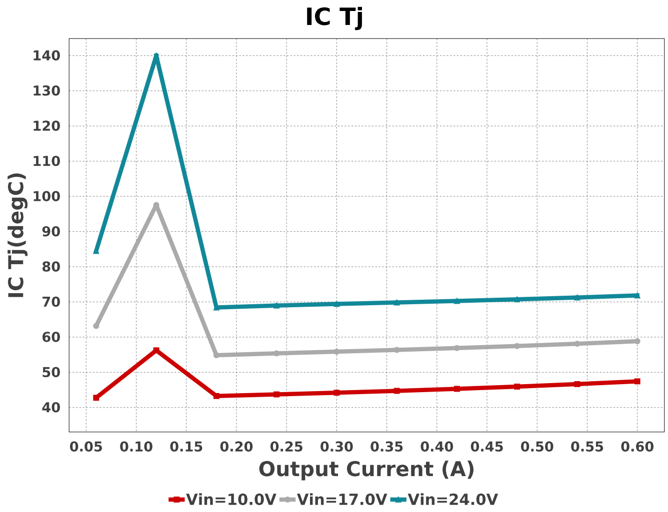


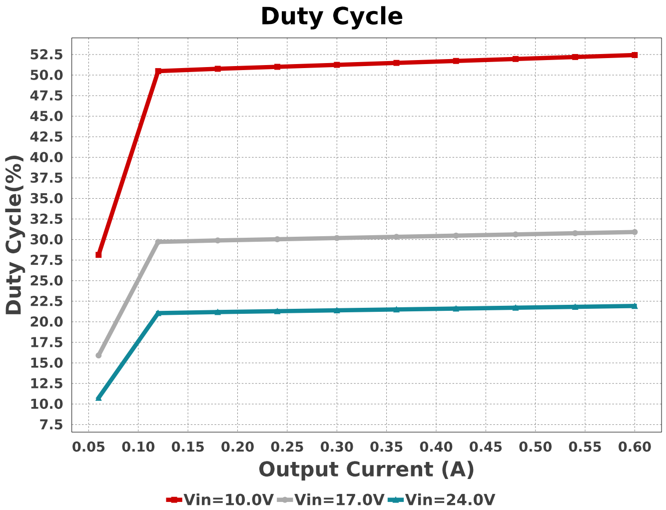
Electrical BOM

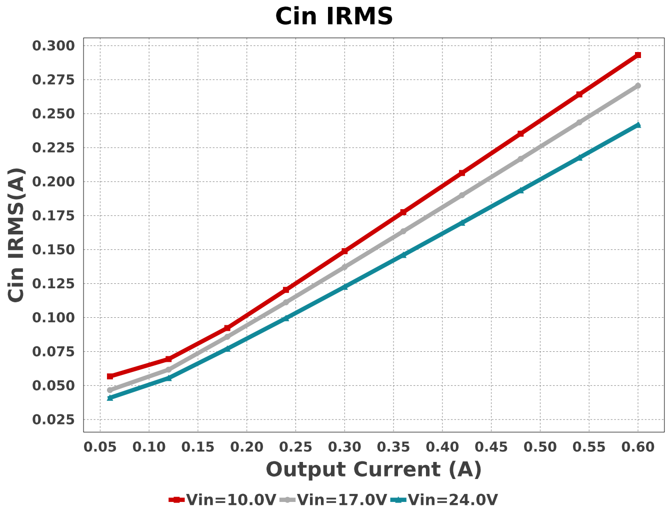
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cboot	MuRata	GRM155R71A104KA01D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	$0.01	0402 3 mm^2
Cff	MuRata	GRM1555C1H3R0CA01D Series= C0G/NP0	Cap= 3.0 pF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 0.0 A	1	$0.01	0402 3 mm^2
Cin	TDK	C2012X5R1H475K125AB Series= X5R	Cap= 4.7 uF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 4.3 A	1	$0.18	0805 7 mm^2
Cinx	TDK	CGA2B3X7R1H104K050BB Series= X7R	Cap= 100.0 nF ESR= 39.064 mOhm VDC= 50.0 V IRMS= 814.67 mA	1	$0.02	0402 3 mm^2
Cinx2	TDK	CGA2B3X7R1H104K050BB Series= X7R	Cap= 100.0 nF ESR= 39.064 mOhm VDC= 50.0 V IRMS= 814.67 mA	1	$0.02	0402 3 mm^2
Cout	MuRata	GRM21BD70J226ME44L Series= X7T	Cap= 22.0 uF ESR= 1.0 mOhm VDC= 6.3 V IRMS= 6.0 A	1	$0.10	0805 7 mm^2
Cvcc	Taiyo Yuden	LMK212B7105KG-T Series= X7R	Cap= 1.0 uF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	$0.02	0805 7 mm^2
L1	NIC Components	NPI43C8R2MTRF	L= 8.2 µH 150.0 mOhm	1	$0.09	IND_NPI43C 31 mm^2
Rfbb	Vishay-Dale	CRCW040224K9FKED Series= CRCW..e3	Res= 24.9 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm^2
Rfbt	Vishay-Dale	CRCW0402100KFKED Series= CRCW..e3	Res= 100.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm^2

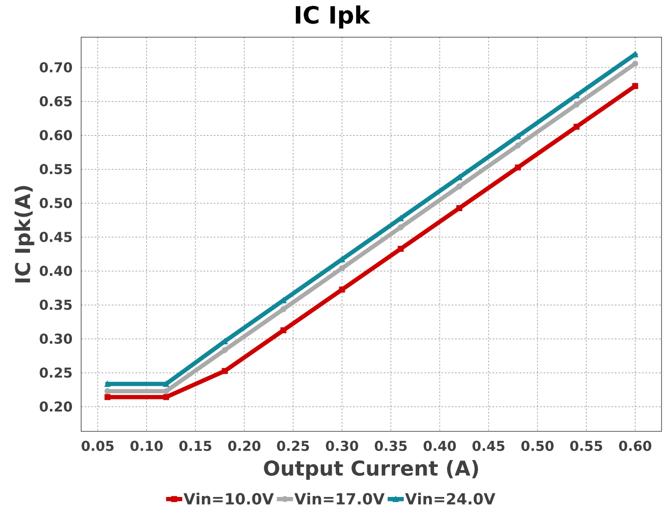
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
U1	Texas Instruments	LMR36006CRNXR	Switcher	1	$0.74	RNX0012B 12 mm²

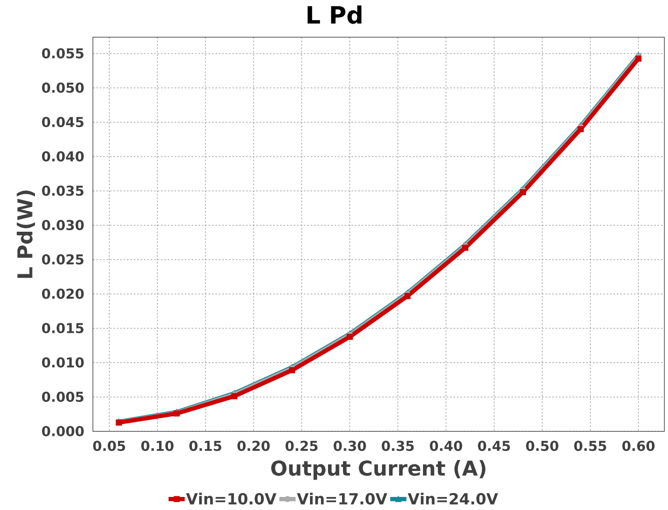


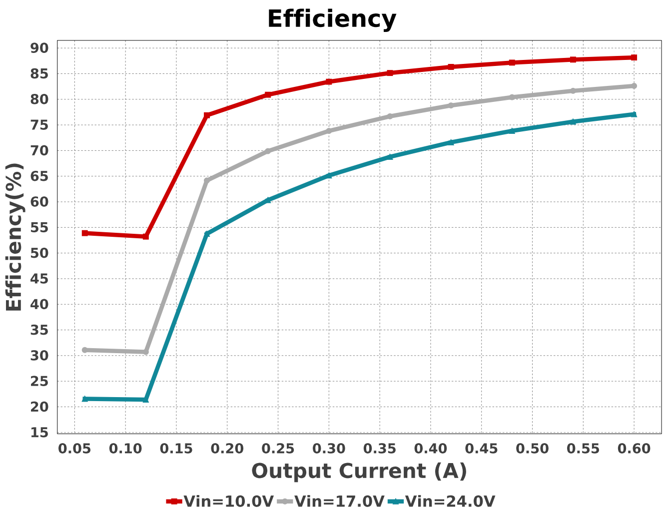


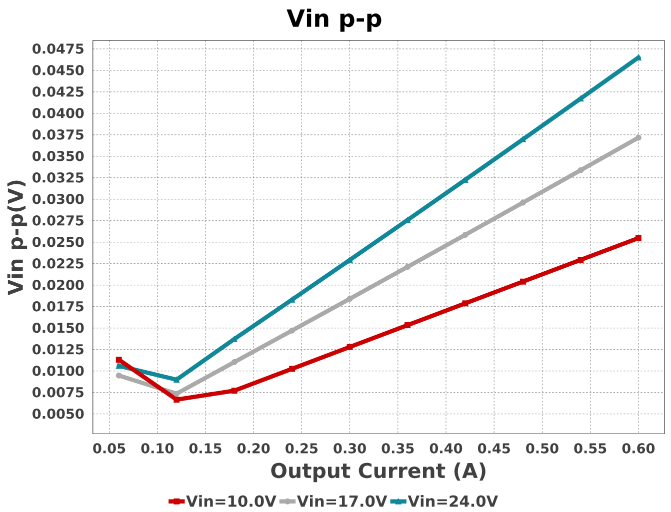


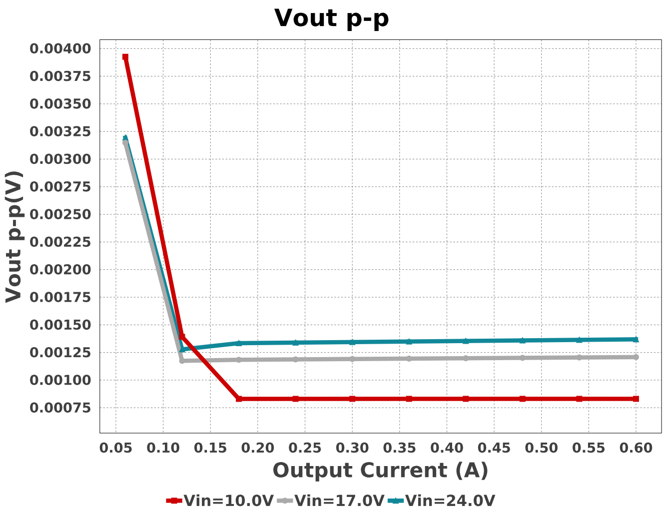


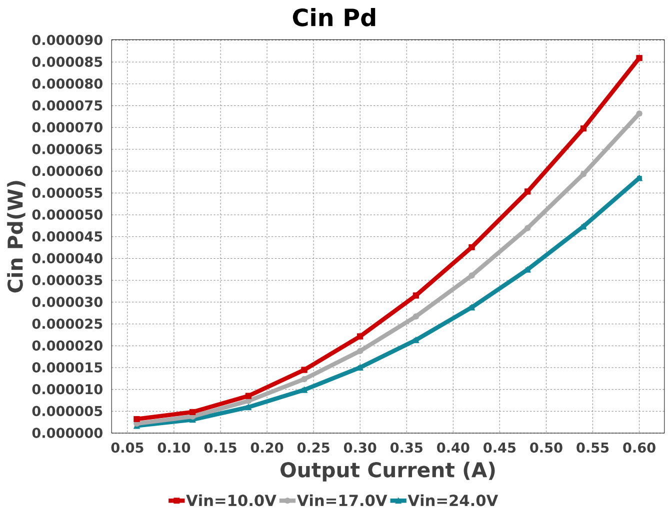


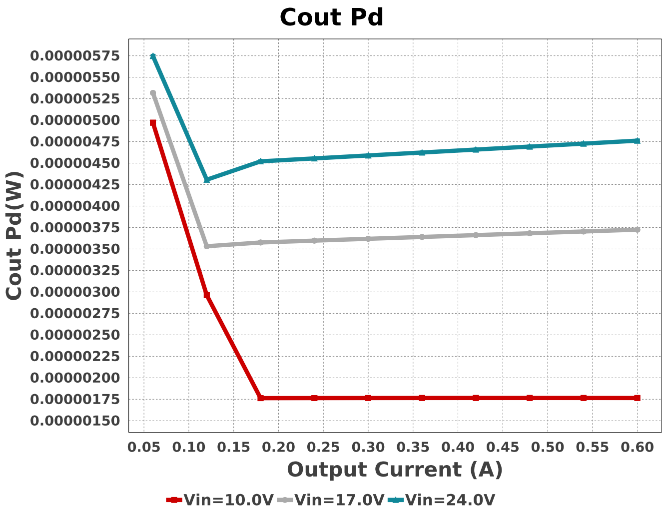


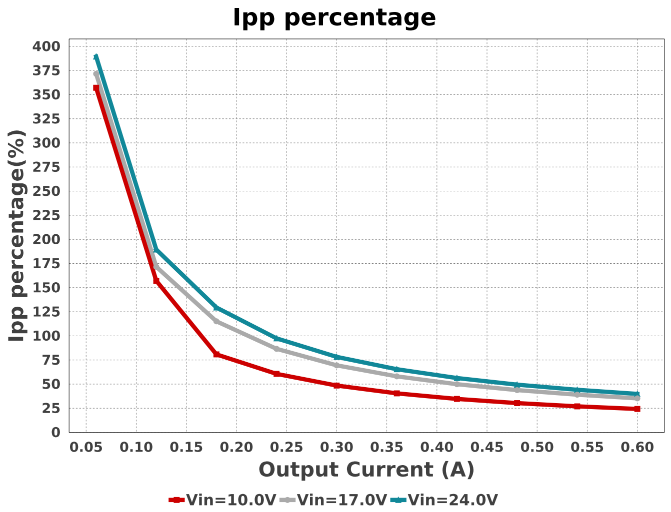

Efficiency
Efficiency(%)
Output Current (A)
Vin=10.0V Vin=17.0V Vin=24.0V

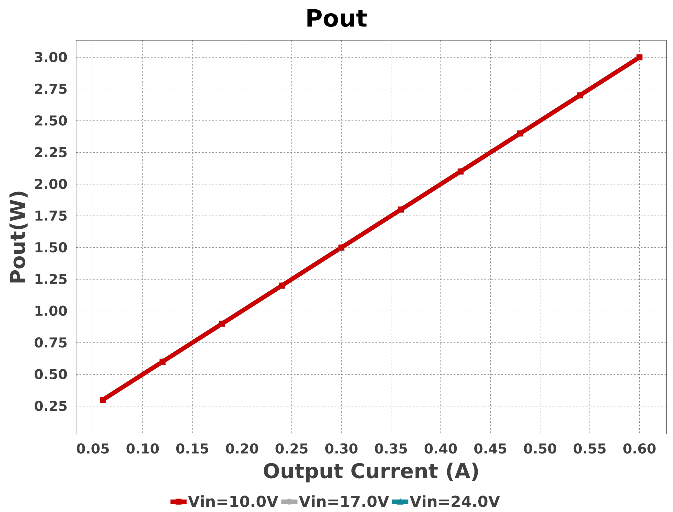

Vin p-p
Vin p-p(V)
Output Current (A)
Vin=10.0V Vin=17.0V Vin=24.0V

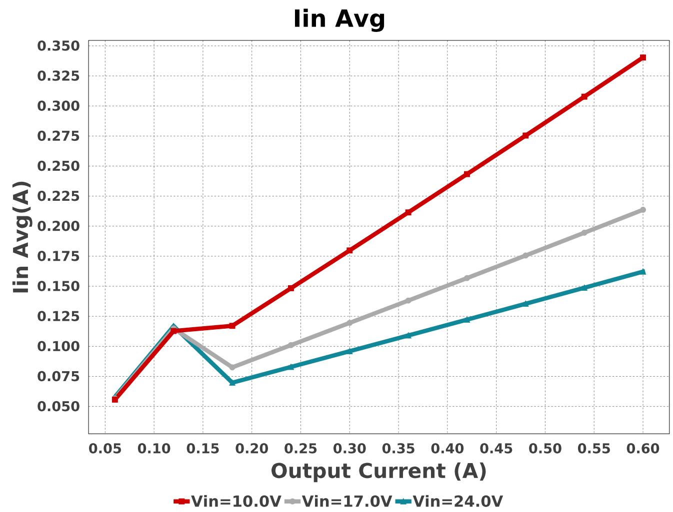

Vout p-p
Vout p-p(V)
Output Current (A)
Vin=10.0V Vin=17.0V Vin=24.0V

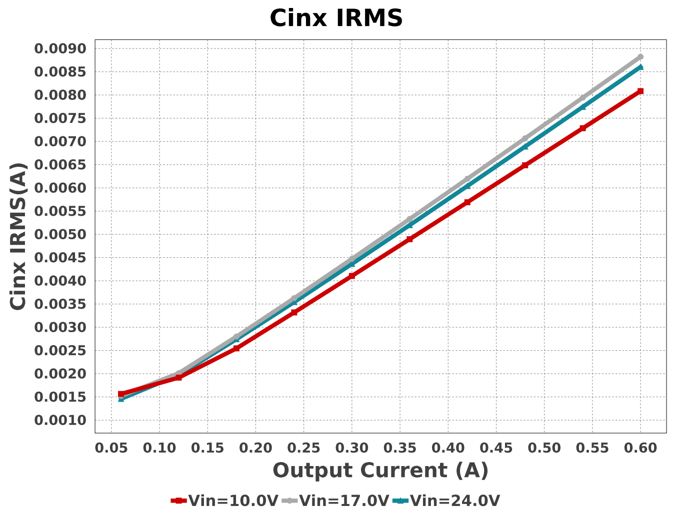

Cin Pd
Cin Pd(W)
Output Current (A)
Vin=10.0V Vin=17.0V Vin=24.0V

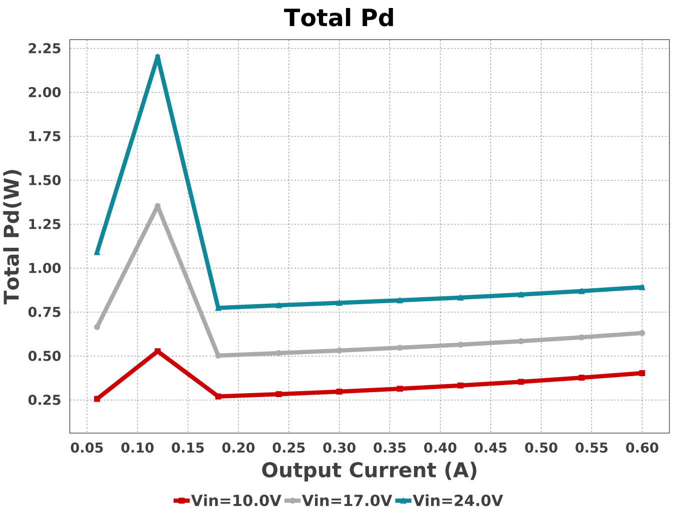

Cout Pd
Cout Pd(W)
Output Current (A)
Vin=10.0V Vin=17.0V Vin=24.0V

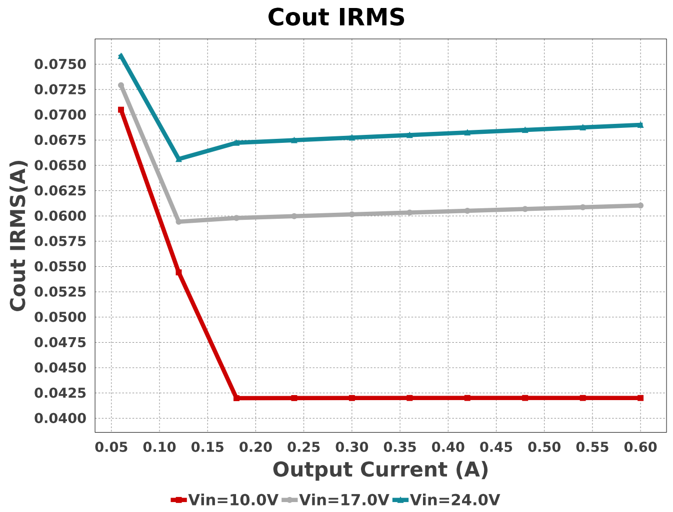

Ipp percentage
Ipp percentage(%)
Output Current (A)
Vin=10.0V Vin=17.0V Vin=24.0V

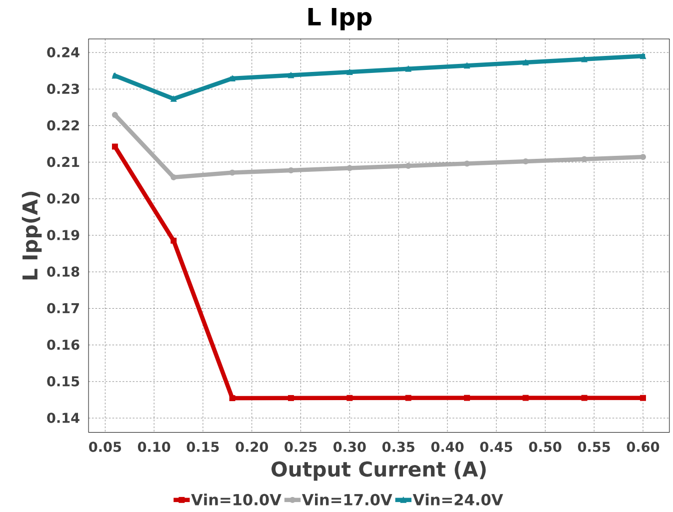

Pout
Pout(W)
Output Current (A)
Vin=10.0V Vin=17.0V Vin=24.0V

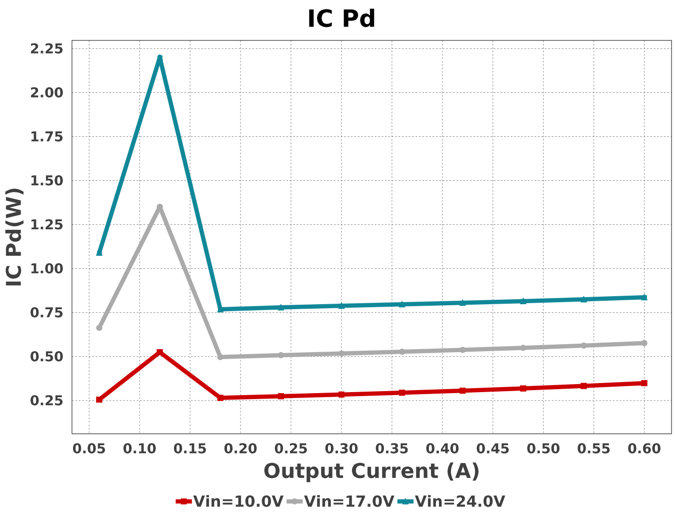

Iin Avg
Iin Avg(A)
Output Current (A)
Vin=10.0V Vin=17.0V Vin=24.0V

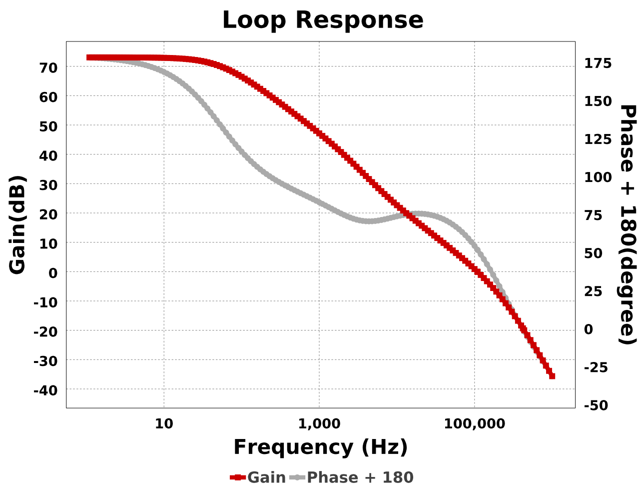

Cinx IRMS
Cinx IRMS(A)
Output Current (A)
Vin=10.0V Vin=17.0V Vin=24.0V

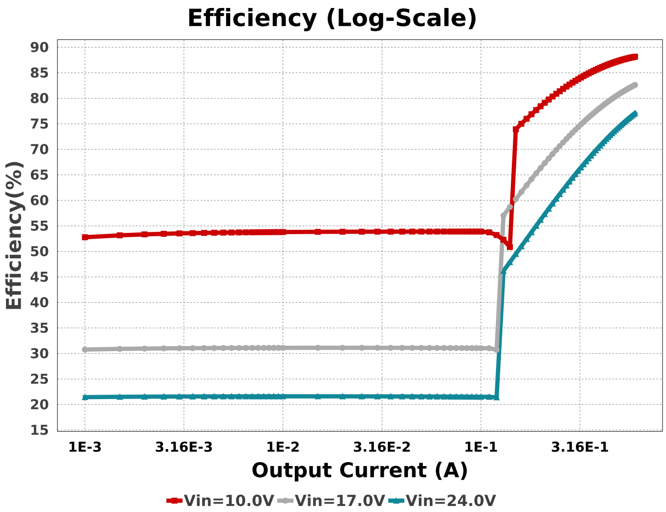

Total Pd
Total Pd(W)
Output Current (A)
Vin=10.0V Vin=17.0V Vin=24.0V


Cout IRMS
Cout IRMS(A)
Output Current (A)
Vin=10.0V Vin=17.0V Vin=24.0V


L Ipp
L Ipp(A)
Output Current (A)
Vin=10.0V Vin=17.0V Vin=24.0V







Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	241.729 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	58.433 µW	Capacitor	Input capacitor power dissipation
3.	Cinx IRMS	8.604 mA	Capacitor	Bulk capacitor RMS ripple current
4.	Cinx Pd	2.892 µW	Capacitor	Bulk capacitor power dissipation
5.	Cout IRMS	69.003 mA	Capacitor	Output capacitor RMS ripple current
6.	Cout Pd	4.761 µW	Capacitor	Output capacitor power dissipation
7.	IC Ipk	719.516 mA	IC	Peak switch current in IC
8.	IC Pd	836.8 mW	IC	IC power dissipation
9.	IC Tj	71.84 degC	IC	IC junction temperature
10.	IC Tolerance	20.0 mV	IC	IC Feedback Tolerance
11.	ICThetaJA Effective	50.0 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance
12.	Iin Avg	162.16 mA	IC	Average input current
13.	Ipp percentage	39.839 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
14.	L Ipp	239.03 mA	Inductor	Peak-to-peak inductor ripple current
15.	L Pd	54.714 mW	Inductor	Inductor power dissipation
16.	Cin Pd	58.433 µW	Power	Input capacitor power dissipation
17.	Cinx Pd	2.892 µW	Power	Bulk capacitor power dissipation
18.	Cout Pd	4.761 µW	Power	Output capacitor power dissipation
19.	IC Pd	836.8 mW	Power	IC power dissipation
20.	L Pd	54.714 mW	Power	Inductor power dissipation
21.	Total Pd	891.776 mW	Power	Total Power Dissipation
22.	BOM Count	11	System Information	Total Design BOM count
23.	Cross Freq	108.592 kHz	System Information	Bode plot crossover frequency
24.	Duty Cycle	21.924 %	System Information	Duty cycle
25.	Efficiency	77.086 %	System Information	Steady state efficiency
26.	FootPrint	81.0 mm^2	System Information	Total Foot Print Area of BOM components

#	Name	Value	Category	Description
27.	Frequency	2.1 MHz	System Information	Switching frequency
28.	Gain Marg	-19.324 dB	System Information	Bode Plot Gain Margin
29.	Iout	600.0 mA	System Information	Iout operating point
30.	Low Freq Gain	73.047 dB	System Information	Gain at 1Hz
31.	Mode	CCM	System Information	Conduction Mode
32.	Phase Marg	52.463 deg	System Information	Bode Plot Phase Margin
33.	Pout	3.0 W	System Information	Total output power
34.	Total BOM	$1.21	System Information	Total BOM Cost
35.	Vin	24.0 V	System Information	Vin operating point
36.	Vin p-p	46.5 mV	System Information	Peak-to-peak input voltage
37.	Vout	5.0 V	System Information	Operational Output Voltage
38.	Vout Actual	5.016 V	System Information	Vout Actual calculated based on selected voltage divider resistors
39.	Vout Tolerance	3.65 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
40.	Vout p-p	1.369 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	600.0 m	Maximum Output Current
VinMax	24.0	Maximum input voltage
VinMin	10.0	Minimum input voltage
Vout	5.0	Output Voltage
base_pn	LMR36006C	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

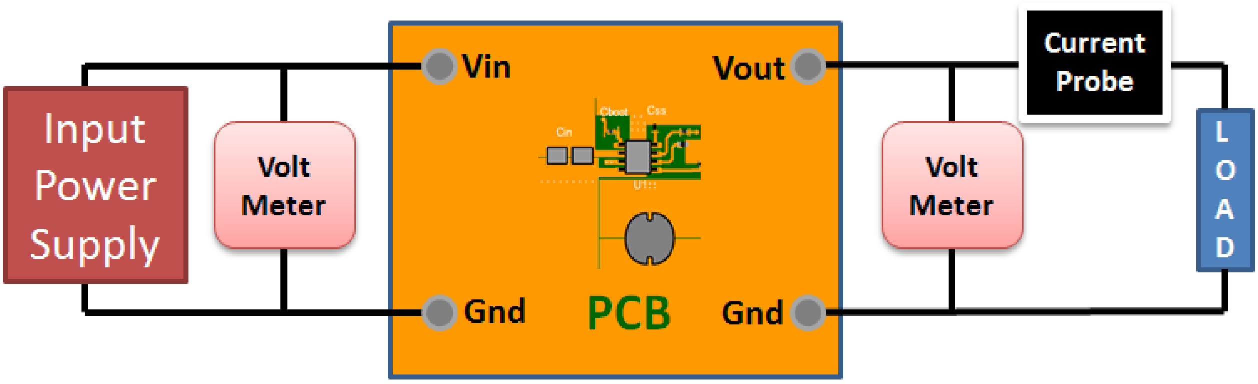
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 10.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum Iout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.

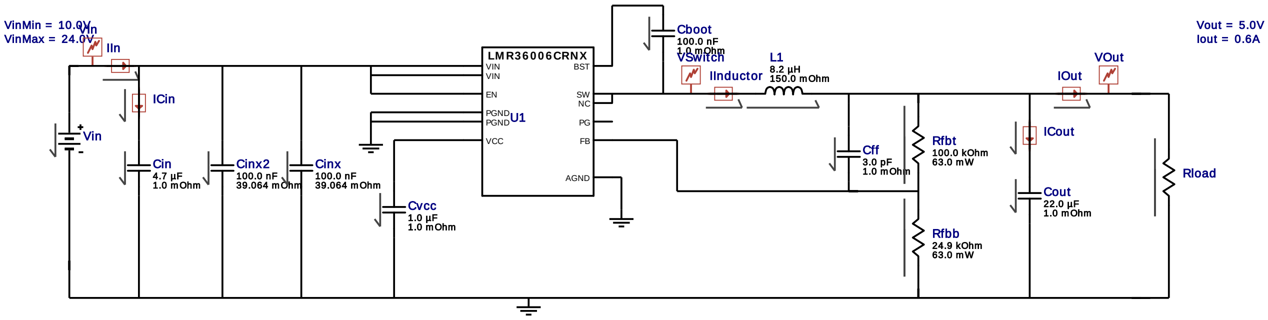


WEBENCH® Electrical Simulation Report

Design Id = 7

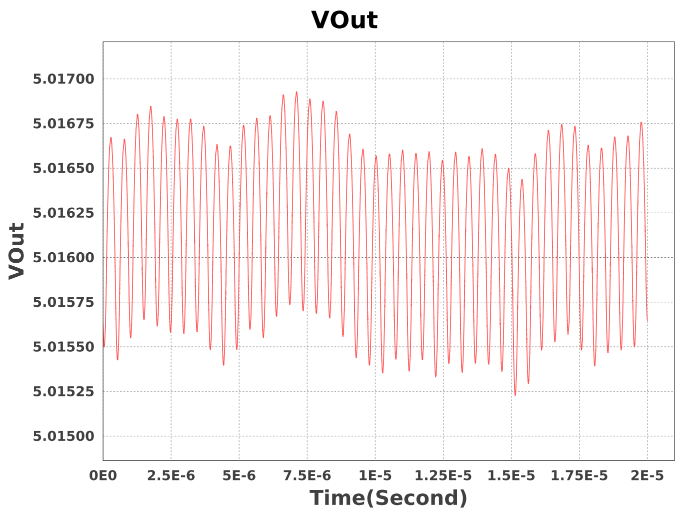
sim_id = 1

Simulation Type = Steady State



Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	Cout	IC	Initial Voltage	5.0
2.	L1	IC	Initial Current	-0.6 A
3.	Rload	R	Load Resistance	8.333333333333334 ohm



Design Assistance

1. Master key : ABE82CB490B2654B[v1]

2. **LMR36006C** Product Folder : http://www.ti.com/product/LMR36006 : contains the data sheet and other resources.